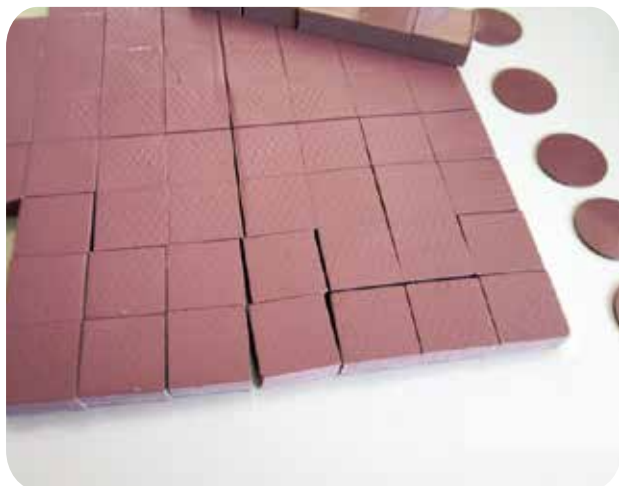




Thermal Silicone Pad



特色 Characteristic

- 具導熱性 Thermal conductive
- 高柔軟性及高壓縮性 High soft and compressible
- 自黏性佳 **Excellent natural tack**
- 高耐電壓值 Good insulator
- 可當緩衝材使用 Shock & vibration absorber
- 多種厚度可選擇 Available in varies thickness

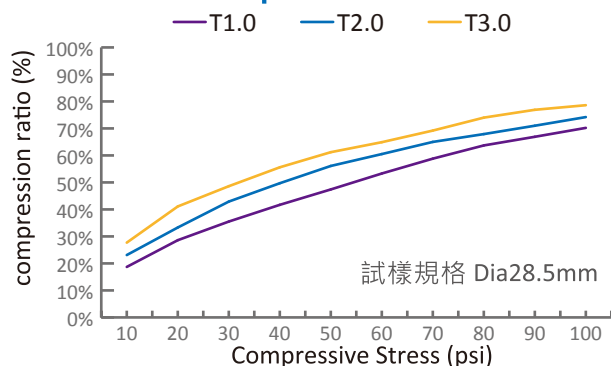
適用範圍 Usage

IC, CPU, GPU, MOS, LED, M/B, PSU, PS, Heat Sink, LCD-TV, CASE, NB, PC, HDD, DDR Module, DVD, etc.

物性 Properties	MP-70	MP-70Y	Unit	Test Method
顏色 Color	Dark red	Pink	---	Visual
厚度 Thickness	0.25~25	0.3~3.0	mm	ASTM D374
導熱係數 Thermal conductivity	7.0	7.0	W/mk	ASTM D5470
比重 Specific Gravity	3.0±0.2	3.24±0.2	g/cm ³	ASTM D792
延展率 Elongation	<250±10	50±10	%	ASTM D412
抗拉強度 Tensile Strength	5±3	1.6	Kgf/cm ²	ASTM D412
硬度 Hardness	10±3	9±2	Shore A	ASTM D2240
重量損失 Weight Loss	<1	-	%	200°C(48hrs)
體積電阻 Volume Resistivity	>10 ¹¹	>10 ¹³	ohm·cm	ASTM D257
耐電壓 Insulation Strength	>4.5	16	KV	ASTM D149
耐溫範圍 Continuous Use Temp	-45~200	-50~200	°C	---

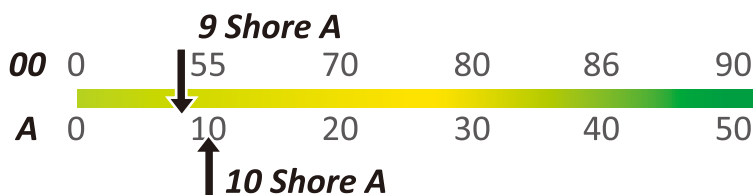
* 測試片標準厚度為1mm以上。 The thickness of the test piece is at least 1 mm.

壓縮測試 Compression Test

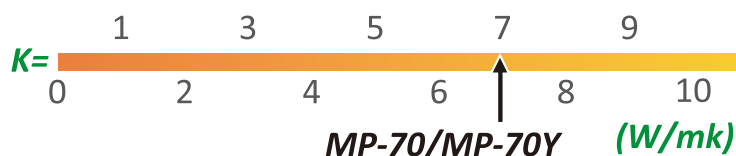


The compression ratio of MP-70 T2.0 at 50 psi is about 56.1%.

蕭氏硬度 Shore Hardness Scales



導熱係數 Thermal conductivity



備註 Remark

- * MP-70 可添加玻璃纖維增強機械性 (P/N: MP-70FG)
- MP-70 can add with fiberglass reinforced.
- * MP-70Y 不能另外加背膠
- The surface of MP-70Y cannot coat with adhesives.